

**3.0Amp. Surface Mount Schottky Barrier Diodes****Ultra Low Forward Voltage****SK34LLSA****Features**

- For surface mounted applications.
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- Plastic material used carries Underwriters Laboratory Flammability Classification 94V-0
- Low leakage current
- Ultra Low V_F
- High surge capability
- High temperature soldering: 250°C/10 seconds at terminals
- Exceeds environmental standards of MIL-S-19500/228

Mechanical Data

- Case: SMA/DO-214AC molded plastic.
- Terminals: Solder plated, solderable per MIL-STD-750 method 2026
- Polarity: Indicated by cathode band.
- Packaging: 12mm tape per EIA STD RS-481.
- Weight: 0.064 gram, 0.002 ounce

Maximum Ratings and Electrical Characteristics

(Rating at 25°C ambient temperature unless otherwise specified.)

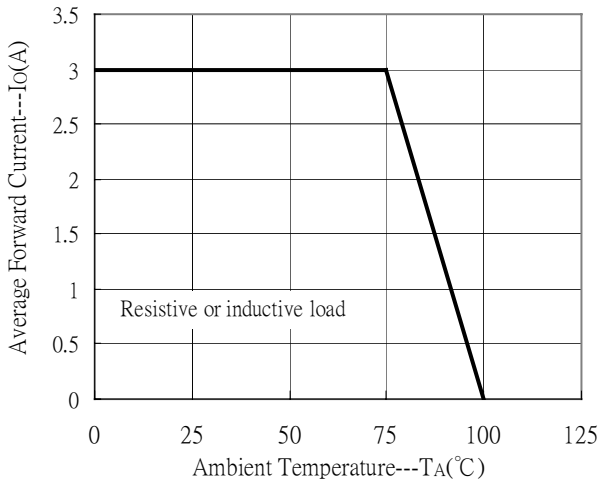
Parameter	Conditions	Symbol	Limit	Units
Repetitive peak reverse voltage		V_{RRM}	40	V
Maximum RMS voltage		V_{RMS}	28	V
Maximum DC blocking voltage		V_R	40	V
Maximum instantaneous forward voltage	$I_F=3A$ (Note 1)	V_F	0.4	V
Maximum average forward rectified current		I_O	3	A
Peak forward surge current	8.3ms single half sine wave superimposed on rated load(JEDEC method)	I_{FSM}	80	A
Maximum DC reverse current	$V_R=V_{RRM}, T_A=25^\circ C$ (Note 1)	I_R	1.5	mA
	$V_R=V_{RRM}, T_A=80^\circ C$ (Note 1)		60	
Maximum thermal resistance	Junction to ambient(Note 2)	$R_{th,JA}$	80 (typ)	°C/w
Diode junction capacitance	f=1MHz and applied 4V reverse voltage	C_J	200 (typ)	pF
Storage temperature		T_{stg}	-50~+125	°C
Operating temperature		T_J	-25~+100	°C

Notes : 1.Pulse test, pulse width=300 μ sec, 2% duty cycle2.Mounted on PCB with 14mm² (0.013mm thickness) copper pad area.

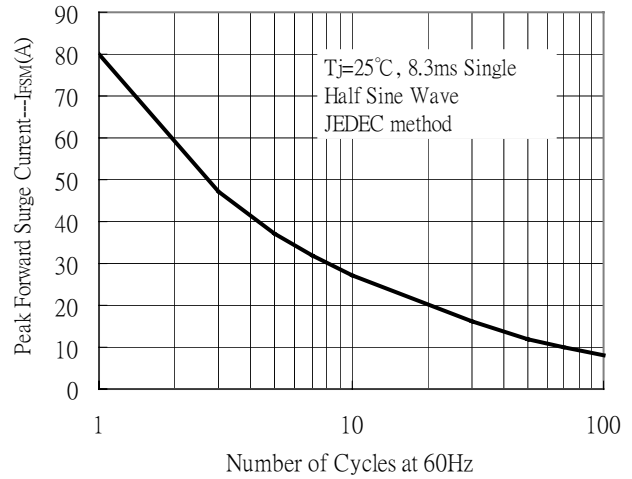


Characteristic Curves

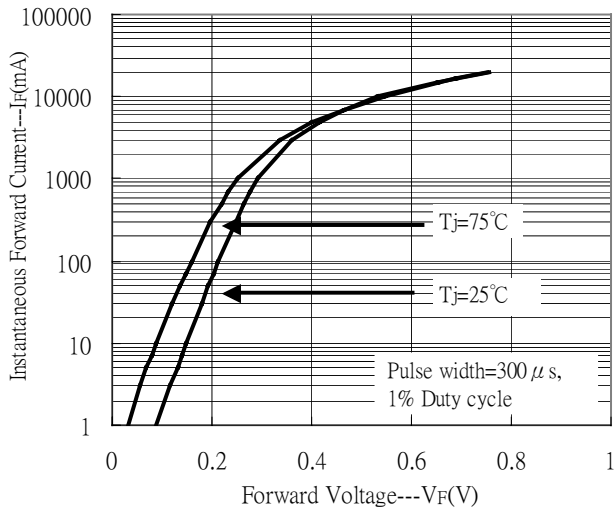
Forward Current Derating Curve



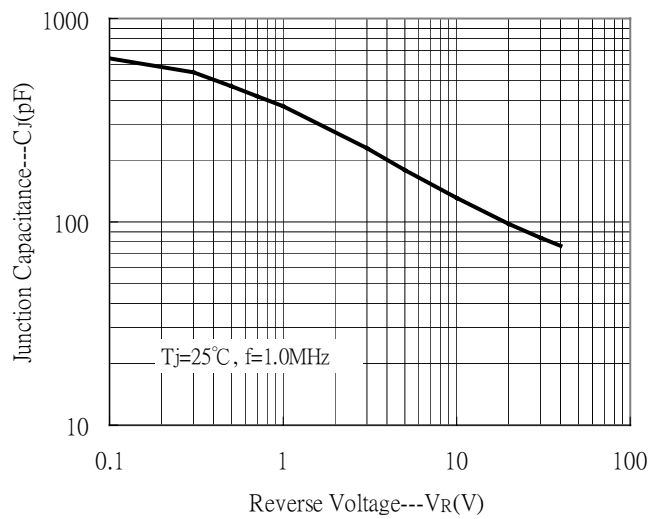
Maximum Non-Repetitive Forward Surge Current



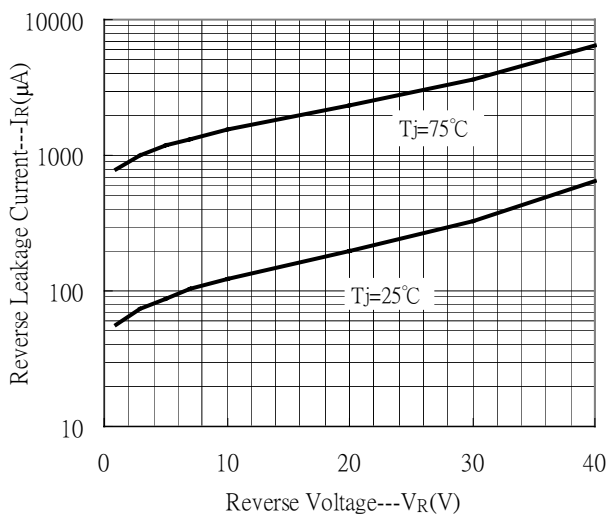
Forward Current vs Forward Voltage



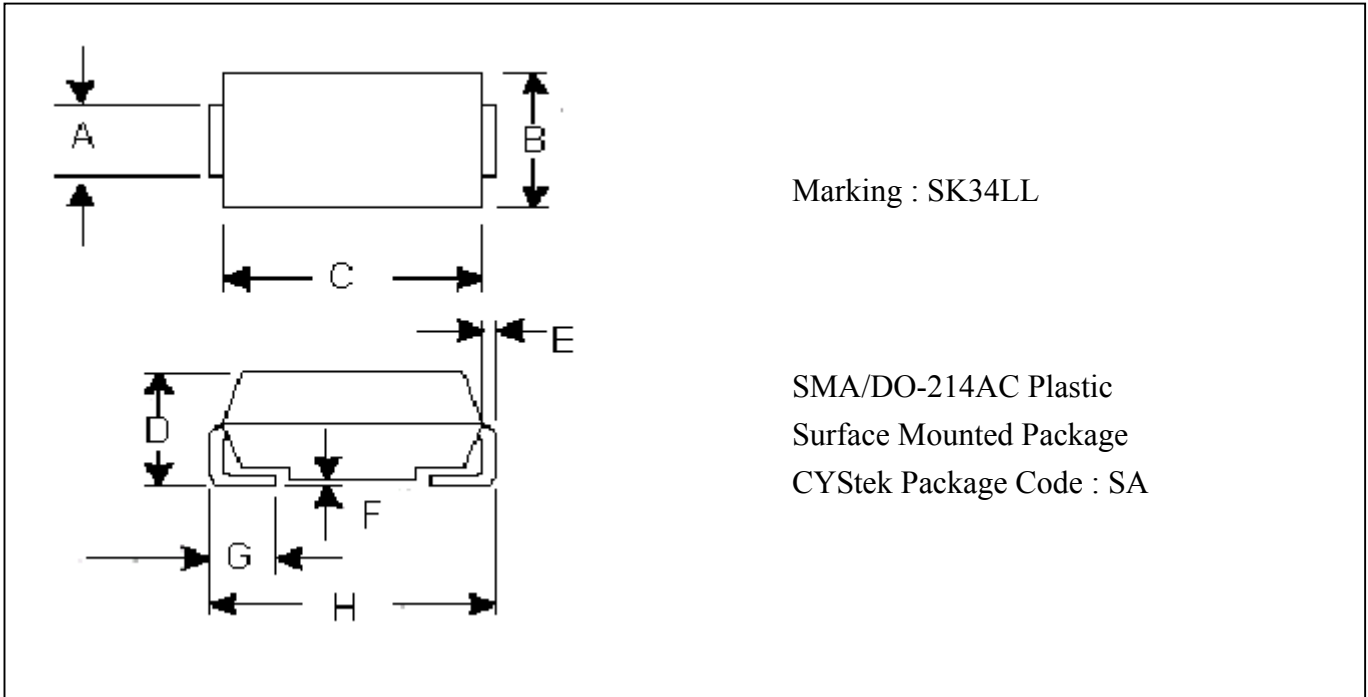
Junction Capacitance vs Reverse Voltage



Reverse Leakage Current vs Reverse Voltage



SMA/DO-214AC Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.055	0.062	1.40	1.60	E	0.005	0.012	0.152	0.305
B	0.098	0.114	2.50	2.90	F	0.002	0.008	0.051	0.203
C	0.157	0.181	4.00	4.60	G	0.030	0.060	0.76	1.52
D	0.076	0.096	2.00	2.44	H	0.188	0.208	4.80	5.28

Notes : 1. Controlling dimension : millimeters.
 2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : Pure tin plated.
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0.

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